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(54) **UTILIZING CHIP-ON-GLASS TECHNOLOGY TO JUMPER ROUTING TRACES**

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H05K 3/22	(2006.01)

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CPC ***G06F 3/044*** (2013.01); ***H05K 1/111*** (2013.01); ***H05K 3/222*** (2013.01); *G06F 2203/04112* (2013.01); *H05K 1/0306* (2013.01); *Y02P 70/611* (2015.11)

(58) **Field of Classification Search**

CPC ... H05K 1/0296; H05K 1/0306; H05K 3/4685
See application file for complete search history.

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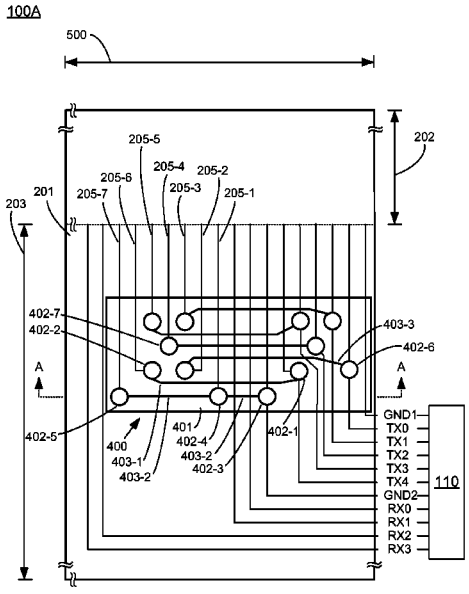
(57) **ABSTRACT**

A chip-on-glass device comprises a chip-on-glass substrate, a metal layer, and a plurality of chip-on-glass connection bumps. The metal layer comprises a plurality of passive jumper routing traces. The plurality of chip-on-glass connection humps is coupled with passive jumper routing traces of the plurality of passive jumper routing traces.

10 Claims, 9 Drawing Sheets